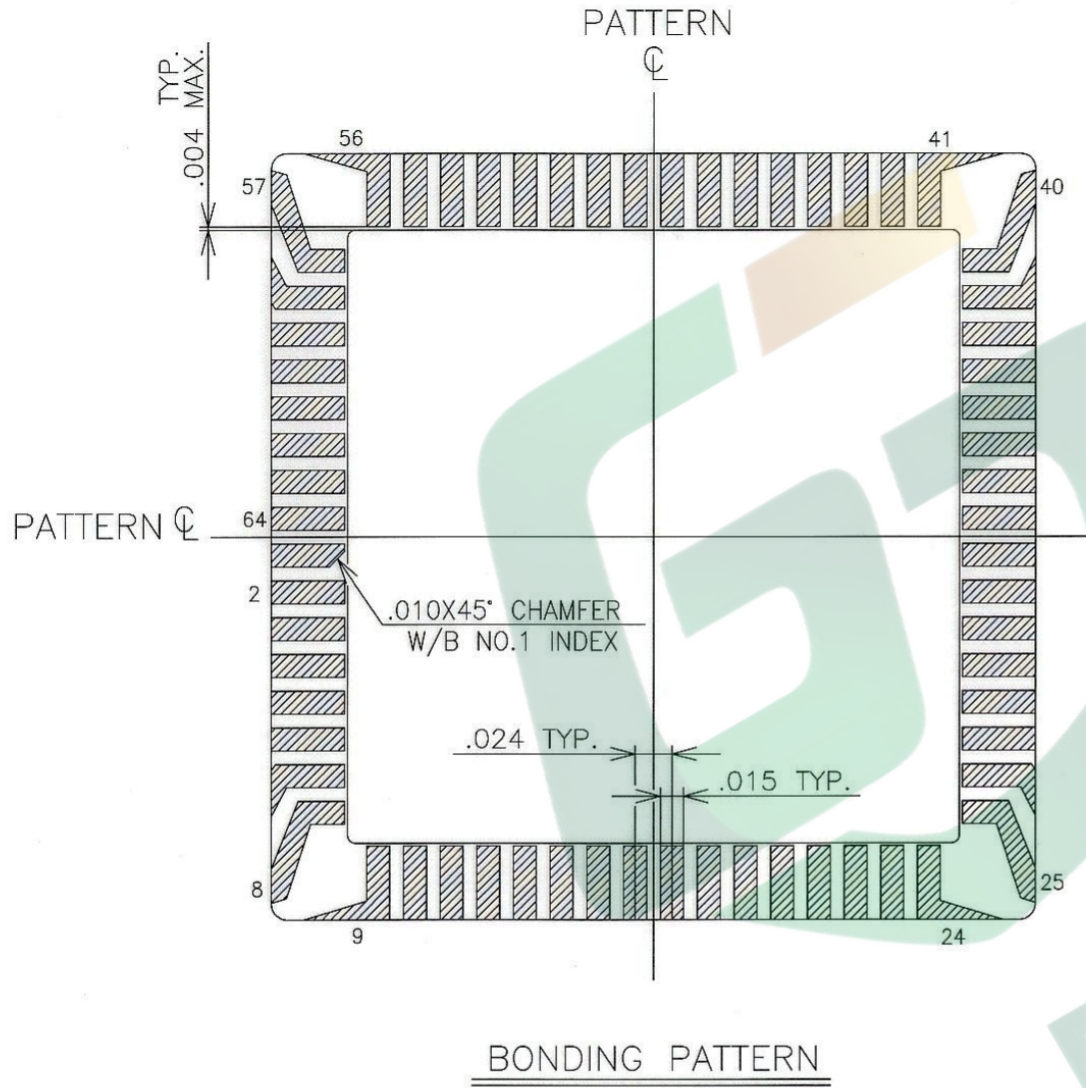


上海季丰电子科技有限公司
 GIGA FORCE ELECTRONICS CO., Limited

制图	胡熠文	Title	DIP64	
核准	何桂港	POD No	POD-SHJF-82	
日期	2023. 3. 2	DIMENSIONS IN:	in	Rev:A



NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.35 OHM MAX.



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